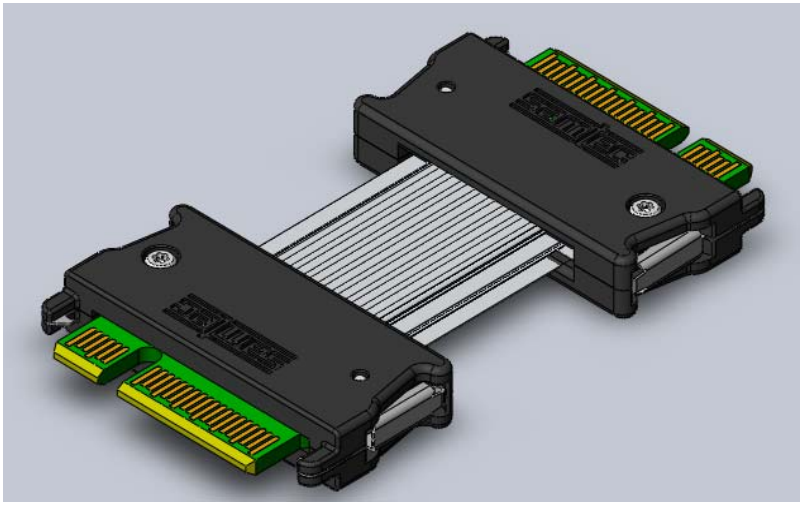
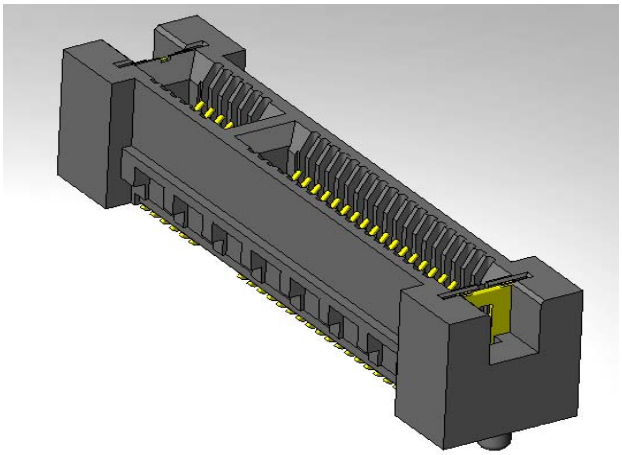
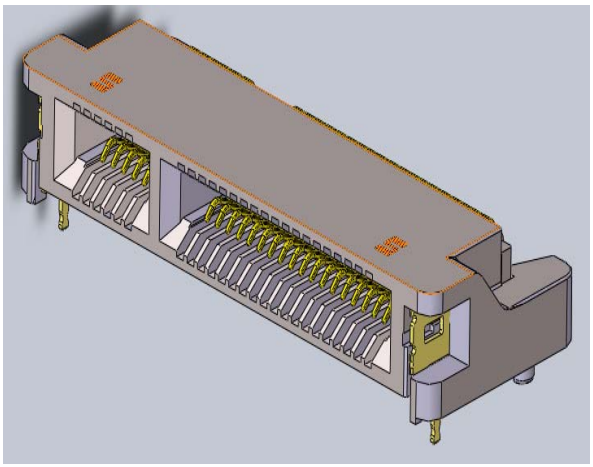
Project Number: Design Qualification Test Report	Tracking Code: 217284_Report_Rev_1			
Requested by: Wy Chiang	Date: 12/28/2012	Product Rev: 1		
Part #: ECDP-016-06.00-LV1-LV1-3-01/ HSEC8-125-01-S-DV-A-L2/ HSEC8-125-01-S-RA	Lot #: N/A	Tech: Peter Chen	Eng: Vico Zhao	
Part description: ECDP / HSEC8		Qty to test: 60		
Test Start: 9/1/2012	Test Completed: 10/10/2012			







Design Qualification Test Report

ECDP / HSEC8

ECDP-016-06.00-LV1-LV1-3-01/ HSEC8-125-01-S-DV-A-L2 /HSEC8-125-01-S-RA

REVISION HISTORY

DATA	REV.NUM.	DESCRIPTION	ENG
11/29/2012	**1**	**Initial Issue**	**PC**

CERTIFICATION

All instruments and measuring equipment were calibrated to National Institute for Standards and Technology (NIST) traceable standards according to IS0 10012-l and ANSI/NCSL 2540-1, as applicable.

SCOPE

To perform the following tests: Design Qualification Test, Please see test plan.

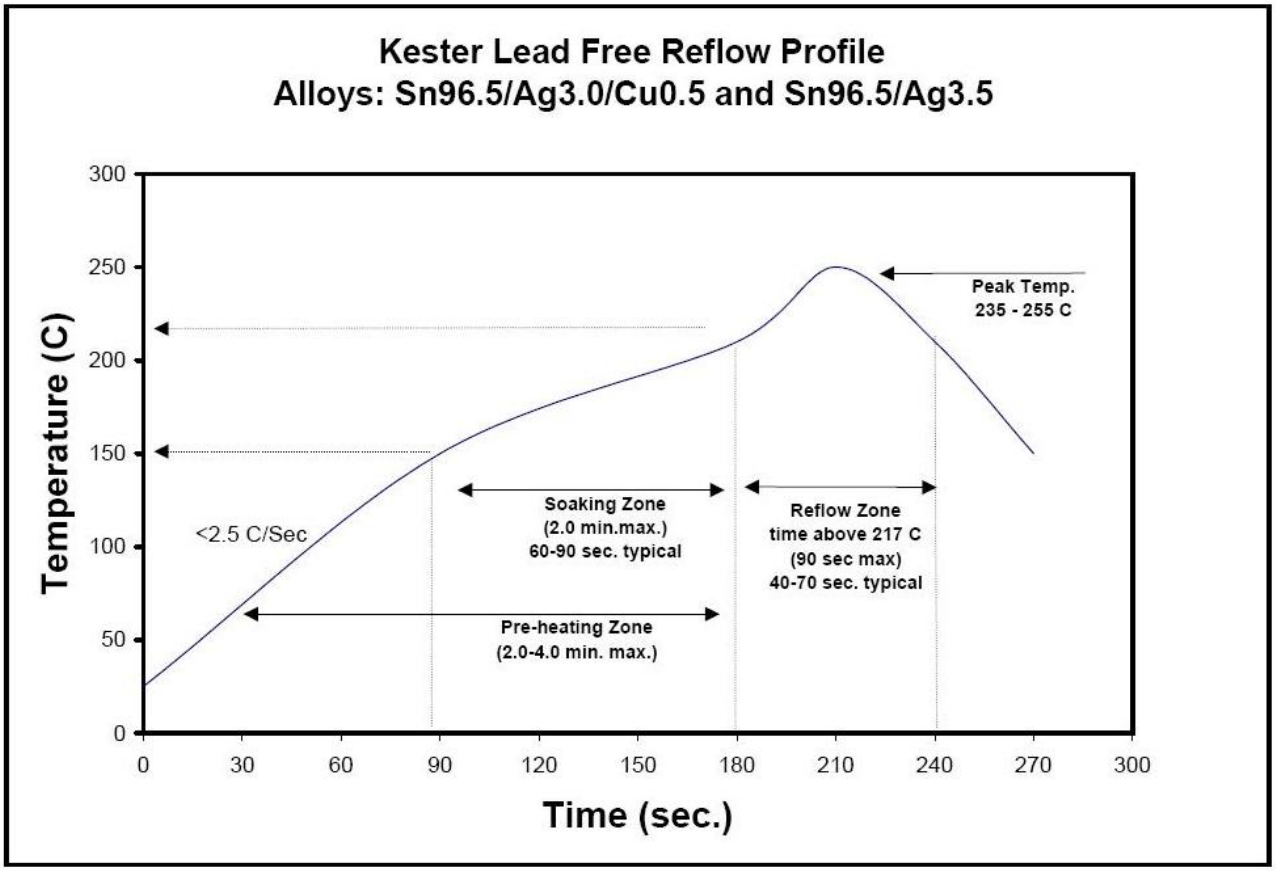
APPLICABLE DOCUMENTS

Standards: EIA Publication 364

TEST SAMPLES AND PREPARATION

1) All materials were manufactured in accordance with the applicable product specification.
2) All test samples were identified and encoded to maintain traceability throughout the test sequences.
3) After soldering, the parts to be used for LLCR and DWV/IR testing were cleaned according to TLWI-0001.
4) Either an automated cleaning procedure or an ultrasonic cleaning procedure may be used.
5) The automated procedure is used with aqueous compatible soldering materials.
6) Parts not intended for testing LLCR and DWV/IR are visually inspected and cleaned if necessary.
7) Any additional preparation will be noted in the individual test sequences.
8) Solder Information: Lead free
9) Re-Flow Time/Temp: See accompanying profile.
10) Samtec Test PCBs used: PCB-103987-TST

TYPICAL OVEN PROFILE (Soldering Parts to Test Boards)



FLOWCHARTS

Gas Tight

TEST STEP	GROUP A 192 Points
01	LLCR-1
02	Gas Tight
03	LLCR-2

Gas Tight = EIA-364-36A

LLCR = EIA-364-23, LLCR

use Keithley 580 in the dry circuit mode, 10 mA Max

Thermal Aging

TEST STEP	GROUP A1 8 Boards Thermal Aging (Mated)
01	Contact Gaps
02	Forces - Mating / Unmating
03	LLCR-1
04	Thermal Aging (Mated and Undisturbed)
05	LLCR-2
06	Forces - Mating / Unmating
07	Contact Gaps

Thermal Aging = EIA-364-17, Test Condition 4 (105°C)

Time Condition 'B' (250 Hours)

Mating / Unmating Forces = EIA-364-13

Contact Gaps / Height - No standard method. Usually measured optically.

LLCR = EIA-364-23, LLCR

20 mV Max, 100 mA Max

Use Keithley 580 or 3706 in 4 wire dry circuit mode

FLOWCHARTS Continued

Durability/Mating/Unmating/Gaps

TEST STEP	GROUP B1 8 Boards (largest position submitted)
01	Contact Gaps
02	LLCR-1
03	Forces - Mating / Unmating
04	25 Cycles
05	Forces - Mating / Unmating
06	25 Cycles (50 Total)
07	Forces - Mating / Unmating
08	25 Cycles (75 Total)
09	Forces - Mating / Unmating
10	25 Cycles (100 Total)
11	Forces - Mating / Unmating
12	Clean w/Compressed Air
13	Contact Gaps
14	LLCR-2
15	Thermal Shock (Mated and Undisturbed)
16	LLCR-3
17	Cyclic Humidity (Mated and Undisturbed)
18	LLCR-4
19	Forces - Mating / Unmating

Thermal Shock = EIA-364-32, Table II, Test Condition I:
-55°C to +85°C 1/2 hour dwell, 100 cycles
Humidity = EIA-364-31, Test Condition B (240 Hours)
and Method III (+25°C to +65°C @ 90% RH to 98% RH)
ambient pre-condition and delete steps 7a and 7b
Mating / Unmating Forces = EIA-364-13
Contact Gaps / Height - No standard method. Usually measured optically.
Gaps to be taken on a minimum of 20% of each part tested
LLCR = EIA-364-23, LLCR
20 mV Max, 100 mA Max
Use Keithley 580 or 3706 in 4 wire dry circuit mode

FLOWCHARTS Continued

IR & DWV

TEST STEP	GROUP A1 2 Mated Sets Break Down Pin-to-Pin	GROUP A2 2 Unmated of Part # Being Tested Break Down Pin-to-Pin	GROUP A3 2 Unmated of Mating Part # Break Down Pin-to-Pin	GROUP B1 2 Mated Sets Pin-to-Pin
01	DWV/Break Down Voltage	DWV/Break Down Voltage	DWV/Break Down Voltage	IR & DWV at test voltage (on both mated sets and on each connector unmated)
02				Thermal Shock (Mated and Undisturbed)
03				IR & DWV at test voltage (on both mated sets and on each connector unmated)
04				Cyclic Humidity (Mated and Undisturbed)
05				IR & DWV at test voltage (on both mated sets and on each connector unmated)

TEST STEP	GROUP E1 2 Mated Sets Break Down Pin-to-Ground	GROUP E2 2 Unmated of Part # Being Tested Break Down Pin-to-Ground	GROUP E3 2 Unmated of Mating Part # Break Down Pin-to-Ground	GROUP F1 2 Mated Sets Pin-to-Ground
01	DWV/Break Down Voltage	DWV/Break Down Voltage	DWV/Break Down Voltage	IR & DWV at test voltage (on both mated sets and on each connector unmated)
02				Thermal Shock (Mated and Undisturbed)
03				IR & DWV at test voltage (on both mated sets and on each connector unmated)
04				Cyclic Humidity (Mated and Undisturbed)
05				IR & DWV at test voltage (on both mated sets and on each connector unmated)

FLOWCHARTS Continued

IR & DWV

TEST STEP	GROUP A1 2 Mated Sets Break Down Row-to-Row	GROUP A2 2 Unmated of Part # Being Tested Break Down Row-to-Row	GROUP A3 2 Unmated of Mating Part # Break Down Row-to-Row	GROUP B1 2 Mated Sets Row-to-Row
01	DWV/Break Down Voltage	DWV/Break Down Voltage	DWV/Break Down Voltage	IR & DWV at test voltage (on both mated sets and on each connector unmated)
02				Thermal Shock (Mated and Undisturbed)
03				IR & DWV at test voltage (on both mated sets and on each connector unmated)
04				Cyclic Humidity (Mated and Undisturbed)
05				IR & DWV at test voltage (on both mated sets and on each connector unmated)

FLOWCHARTS Continued

TEST STEP	GROUP E1 2 Mated Sets Break Down Pin-to-Closest Metallic Hardware	GROUP E2 2 Unmated of Part # Being Tested Break Down Pin-to-Closest Metallic Hardware	GROUP E3 2 Unmated of Mating Part # Break Down Pin-to-Closest Metallic Hardware	GROUP F1 2 Mated Sets Pin-to-Closest Metallic Hardware
01	DWV/Break Down Voltage	DWV/Break Down Voltage	DWV/Break Down Voltage	IR & DWV at test voltage (on both mated sets and on each connector unmated)
02				Thermal Shock (Mated and Undisturbed)
03				IR & DWV at test voltage (on both mated sets and on each connector unmated)
04				Cyclic Humidity (Mated and Undisturbed)
05				IR & DWV at test voltage (on both mated sets and on each connector unmated)

DWV on Group B1 to be performed at Test Voltage

DWV test voltage is equal to 75% of the lowest break down voltage from Groups A1, A2 or A3

Thermal Shock = EIA-364-32, Table II, Test Condition I:

-55°C to +85°C 1/2 hour dwell, 100 cycles

Humidity = EIA-364-31, Test Condition B (240 Hours)

and Method III (+25°C to +65°C @ 90% RH to 98% RH)

ambient pre-condition and delete steps 7a and 7b

IR = EIA-364-21

DWV = EIA-364-20, Test Condition 1

FLOWCHARTS Continued

Current Carrying Capacity - Double Row

TEST STEP	GROUP B1 3 Mated Assemblies 2 Contacts Powered	GROUP B2 3 Mated Assemblies 4 Contacts Powered	GROUP B3 3 Mated Assemblies 6 Contacts Powered	GROUP B4 3 Mated Assemblies 8 Contacts Powered	GROUP B5 3 Mated Assemblies All Contacts Powered
01	CCC	CCC	CCC	CCC	CCC

(TIN PLATING) - Tabulate calculated current at RT, 65°C, 75°C and 95°C
after derating 20% and based on 105°C
(GOLD PLATING) - Tabulate calculated current at RT, 85°C, 95°C and 115°C
after derating 20% and based on 125°C
CCC, Temp rise = EIA-364-70

Mechanical Shock / Vibration / LLCR

TEST STEP	GROUP A1 192 Points
01	LLCR-1
02	Shock
03	Vibration
04	LLCR-2

Mechanical Shock = EIA 364-27 Half Sine,
100 g's, 6 milliSeconds (Condition "C") each axis
Vibration = EIA 364-28, Random Vibration
7.56 g RMS, Condition VB --- 2 hours/axis
LLCR = EIA-364-23, LLCR
20 mV Max, 100 mA Max
Use Keithley 580 or 3706 in 4 wire dry circuit mode

Shock / Vibration / nanoSecond Event Detection

TEST STEP	GROUP A1 60 Points
01	Event Detection, Shock
02	Event Detection, Vibration

Mechanical Shock = EIA 364-27 Half Sine,
100 g's, 6 milliSeconds (Condition "C") each axis
Vibration = EIA 364-28, Random Vibration
7.56 g RMS, Condition VB --- 2 hours/axis
Event detection requirement during Shock / Vibration is 50 nanoseconds minimum

FLOWCHARTS Continued

Connector Pull

TEST STEP	GROUP A1 5 Pieces 0°	GROUP B1 5 Pieces 90°
01	Pull test, Continuity	Pull test, Continuity

Monitor continuity and pull; record forces when continuity fails

Cable Flex Test

TEST STEP	GROUP B1 8 Cable Assemblies Flat Cable
01	IR & DWV at test voltage
02	Flex 500 Cycles
03	Visual Inspection
04	IR & DWV at test voltage

DWV to be performed at Test Voltage

DWV test voltage is equal to 75% of the lowest break down voltage from 'Sequence E'

*** If 'Sequence E' is not being tested, then separate parts must be broken down to establish the test voltage**

Monitor continuity during flex testing on all groups

Cable Flex Test = EIA-364-41D

Circular Jacket Cable - to be tested 90° each direction (180° total)

EIA-364-41D min flex requirement = 200 cycles

Flat Cable - to be tested 70°±5° each direction (140°±10° total)

EIA-364-41D min flex requirement = 500 cycles

IR = EIA-364-21

DWV = EIA-364-20, Test Condition 1

ATTRIBUTE DEFINITIONS

The following is a brief, simplified description of attributes.

THERMAL SHOCK:

1) EIA-364-32, *Thermal Shock (Temperature Cycling) Test Procedure for Electrical Connectors.*
2) Test Condition 1: -55°C to +85°C
3) Test Time: ½ hour dwell at each temperature extreme
4) Number of Cycles: 100
5) All test samples are pre-conditioned at ambient.
6) All test samples are exposed to environmental stressing in the mated condition.

THERMAL:

1) EIA-364-17, *Temperature Life with or without Electrical Load Test Procedure for Electrical Connectors.*
2) Test Condition 4 at 105° C.
3) Test Time Condition B for 250 hours.
4) All test samples are pre-conditioned at ambient.
5) All test samples are exposed to environmental stressing in the mated condition.

HUMIDITY:

1) Reference document: EIA-364-31, *Humidity Test Procedure for Electrical Connectors.*
2) Test Condition B, 240 Hours.
3) Method III, +25° C to + 65° C, 90% to 98% Relative Humidity excluding sub-cycles 7a and 7b.
4) All samples are pre-conditioned at ambient.
5) All test samples are exposed to environmental stressing in the mated condition.

MECHANICAL SHOCK (Specified Pulse):

1) Reference document: EIA-364-27, *Mechanical Shock Test Procedure for Electrical Connectors*
2) Test Condition C
3) Peak Value: 100 G
4) Duration: 6 Milliseconds
5) Wave Form: Half Sine
6) Velocity: 12.3 ft/s
7) Number of Shocks: 3 Shocks / Direction, 3 Axis (18 Total)

VIBRATION:

1) Reference document: EIA-364-28, *Vibration Test Procedure for Electrical Connectors*
2) Test Condition V, Letter B
3) Power Spectral Density: 0.04 G^2 / Hz
4) G 'RMS': 7.56
5) Frequency: 50 to 2000 Hz
6) Duration: 2.0 Hours per axis (3 axis total)

NANOSECOND-EVENT DETECTION:

1) Reference document: EIA-364-87, *Nanosecond-Event Detection for Electrical Connectors*
2) Prior to test, the samples were characterized to assure the low nanosecond event being monitored will trigger the detector.
3) After characterization it was determined the test samples could be monitored for 50 nanosecond events

ATTRIBUTE DEFINITIONS

The following is a brief, simplified description of attributes.

MATING/UNMATING:

1) Reference document: EIA-364-13, *Mating and Unmating Forces Test Procedure for Electrical Connectors*.
2) The full insertion position was to within 0.003" to 0.004" of the plug bottoming out in the receptacle to prevent damage to the system under test.
3) One of the mating parts is secured to a floating X-Y table to prevent damage during cycling.

INSULATION RESISTANCE (IR):

To determine the resistance of insulation materials to leakage of current through or on the surface of these materials when a DC potential is applied.

1) PROCEDURE:
    a. Reference document: EIA-364-21, *Insulation Resistance Test Procedure for Electrical Connectors*.
    b. Test Conditions:
        i. Between Adjacent Contacts or Signal-to-Ground
        ii. Electrification Time 2.0 minutes
        iii. Test Voltage (500 VDC) corresponds to calibration settings for measuring resistances.
2) MEASUREMENTS:
3) When the specified test voltage is applied (VDC), the insulation resistance shall not be less than 1000 megohms.

DIELECTRIC WITHSTANDING VOLTAGE (DWV):

To determine if the sockets can operate at its rated voltage and withstand momentary over potentials due to switching, surges, and other similar phenomenon. Separate samples are used to evaluate the effect of environmental stresses so not to influence the readings from arcing that occurs during the measurement process.

1) PROCEDURE:
    a. Reference document: EIA-364-20, *Withstanding Voltage Test Procedure for Electrical Connectors*.
    b. Test Conditions:
        i. Between Adjacent Contacts or Signal-to-Ground
        ii. Rate of Application 500 V/Sec
        iii. Test Voltage (VAC) until breakdown occurs
2) MEASUREMENTS/CALCULATIONS
    a. The breakdown voltage shall be measured and recorded.
    b. The dielectric withstanding voltage shall be recorded as 75% of the minimum breakdown voltage.
    c. The working voltage shall be recorded as one-third (1/3) of the dielectric withstanding voltage (one-fourth of the breakdown voltage)..

ATTRIBUTE DEFINITIONS

The following is a brief, simplified description of attributes.

TEMPERATURE RISE (Current Carrying Capacity, CCC):

1) EIA-364-70, *Temperature Rise versus Current Test Procedure for Electrical Connectors and Sockets*.
2) When current passes through a contact, the temperature of the contact increases as a result of I^2R (resistive) heating.
3) The number of contacts being investigated plays a significant part in power dissipation and therefore temperature rise.
4) The size of the temperature probe can affect the measured temperature.
5) Copper traces on PC boards will contribute to temperature rise:
    a. Self heating (resistive)
    b. Reduction in heat sink capacity affecting the heated contacts
6) A de-rating curve, usually 20%, is calculated.
7) Calculated de-rated currents at three temperature points are reported:
    a. Ambient
    b. 80^{o} C
    c. 95^{o} C
    d. 115^{o} C
8) Typically, neighboring contacts (in close proximity to maximize heat build up) are energized.
9) The thermocouple (or temperature measuring probe) will be positioned at a location to sense the maximum temperature in the vicinity of the heat generation area.
10) A computer program, *TR 803.exe*, ensures accurate stability for data acquisition.
11) Hook-up wire cross section is larger than the cross section of any connector leads/PC board traces, jumpers, etc.
12) Hook-up wire length is longer than the minimum specified in the referencing standard.

LLCR:

1) EIA-364-23, *Low Level Contact Resistance Test Procedure for Electrical Connectors and Sockets*.
2) A computer program, *LLCR 221.exe*, ensures repeatability for data acquisition.
3) The following guidelines are used to categorize the changes in LLCR as a result from stressing
    a. <= +5.0 mOhms: ---------- Stable
    b. +5.1 to +10.0 mOhms:---------- Minor
    c. +10.1 to +15.0 mOhms: ---------- Acceptable
    d. +15.1 to +50.0 mOhms: ---------- Marginal
    e. +50.1 to +2000 mOhms: ---------- Unstable
    f. >+2000 mOhms:---------- Open Failure

ATTRIBUTE DEFINITIONS

The following is a brief, simplified description of attributes.

GAS TIGHT:

To provide method for evaluating the ability of the contacting surfaces in preventing penetration of harsh vapors which might lead to oxide formation that may degrade the electrical performance of the contact system.

1) EIA-364-23, *Low Level Contact Resistance Test Procedure for Electrical Connectors and Sockets*.
2) A computer program, *LLCR 221.exe*, ensures repeatability for data acquisition.
3) The following guidelines are used to categorize the changes in LLCR as a result from stressing
    a. <= +5.0 mOhms: ---------- Stable
    b. +5.1 to +10.0 mOhms:---------- Minor
    c. +10.1 to +15.0 mOhms: ---------- Acceptable
    d. +15.1 to +50.0 mOhms: ---------- Marginal
    e. +50.1 to +2000 mOhms: ---------- Unstable
    f. >+2000 mOhms:---------- Open Failure
4) Procedure:
    a. Reference document: EIA-364-36, *Test Procedure for Determination of Gas-Tight Characteristics for Electrical Connectors, Sockets and/or Contact Systems*.
    b. Test Conditions:
        i. Class II--- Mated pairs of contacts assembled to their plastic housings.
        ii. Reagent grade Nitric Acid shall be used of sufficient volume to saturate the test chamber
        iii. The ratio of the volume of the test chamber to the surface area of the acid shall be 10:1.
        iv. The chamber shall be saturated with the vapor for at least 15 minutes before samples are added.
        v. Exposure time, 55 to 65 minutes.
        vi. The samples shall be no closer to the chamber walls than 1 inches and no closer to the surface of the acid than 3 inches.
        vii. The samples shall be dried after exposure for a minimum of 1 hour.
        viii. Drying temperature 50^{o} C
        ix. The final LLCR shall be conducted within 1 hour after drying.

ATTRIBUTE DEFINITIONS

The following is a brief, simplified description of attributes.

CONNECTOR PULL:

1) Secure cable near center and pull on connector
    a. At 90°, right angle to cable
    b. At 0°, in-line with cable

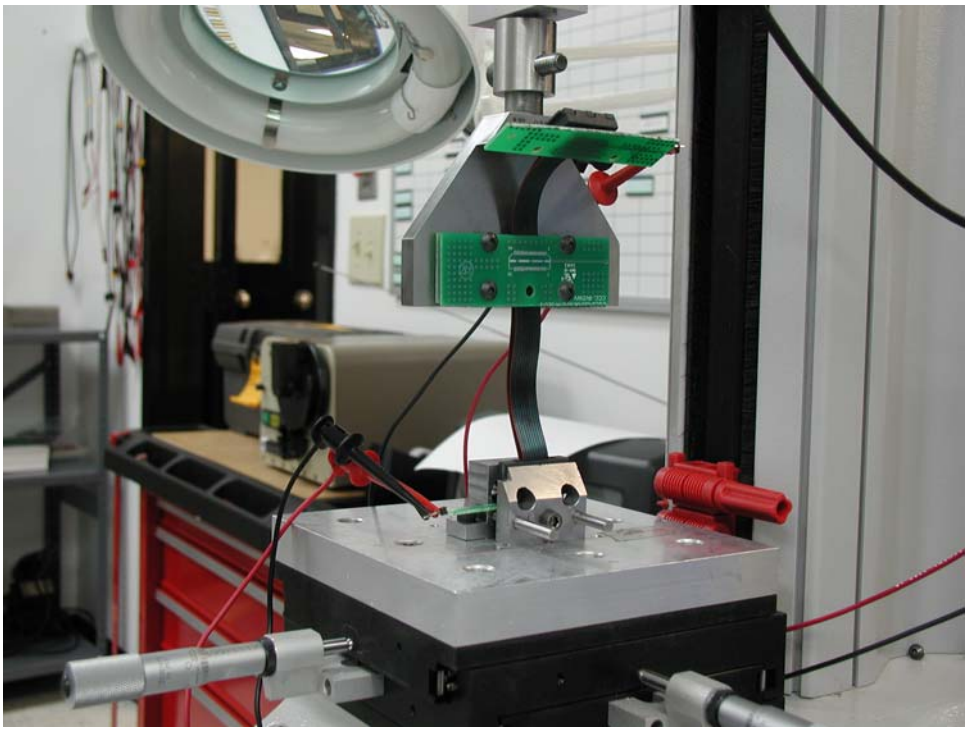


Fig. 1
(Typical set-up, actual part not depicted.)
0° Connector pull, notice the electrical continuity hook-up wires.

ATTRIBUTE DEFINITIONS

The following is a brief, simplified description of attributes.

CABLE DURABILITY:

1) Oscillate and monitor electrical continuity for open circuit indication.
    a. ±70°±5°Pendulum Mode, bend up to 500 cycles with 8 oz. load on cable end.

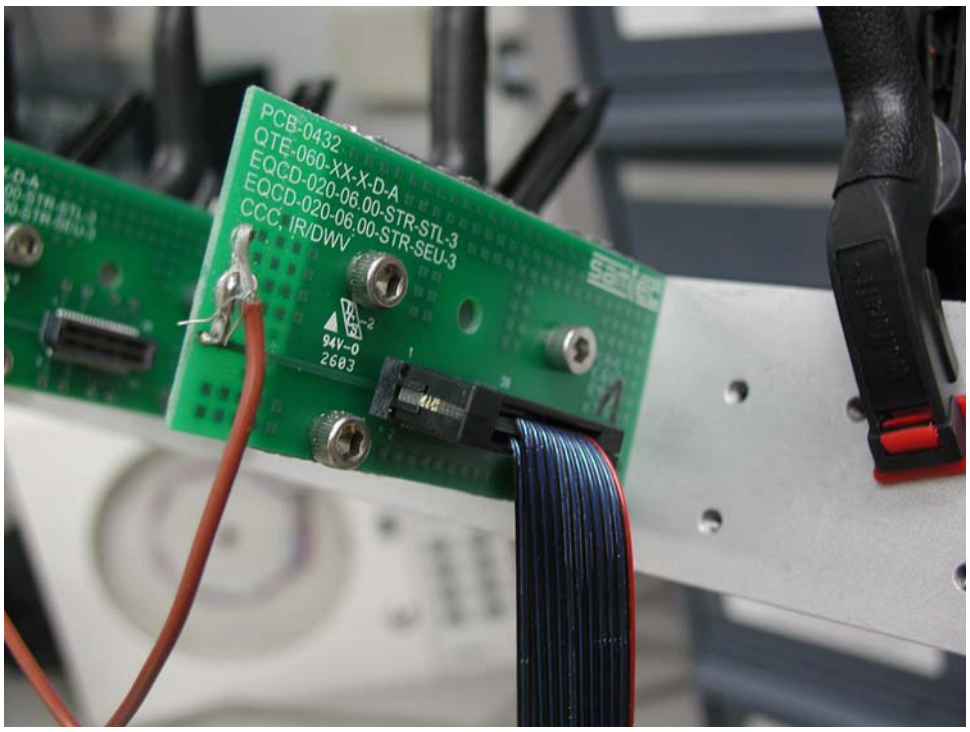


Fig. 2
(Typical set-up, actual part not depicted.)

RESULTS

Temperature Rise, CCC at a 20% de-rating

- **CCC for a 30°C Temperature Rise ---------- 2.3 A per contact with 2 adjacent contacts powered**
- **CCC for a 30°C Temperature Rise ---------- 1.7 A per contact with 4 adjacent contacts powered**
- **CCC for a 30°C Temperature Rise ---------- 1.5 A per contact with 6 adjacent contacts powered**
- **CCC for a 30°C Temperature Rise ---------- 1.3 A per contact with 8 adjacent contacts powered**
- **CCC for a 30°C Temperature Rise ---------- 0.9 A per contact with all adjacent contacts powered**

Mating /unmating force
Thermal aging:

- **Initial**
  - **Mating**
    - **Min ---------- 4.68 Lbs**
    - **Max---------- 5.56 Lbs**
  - **Unmating**
    - **Min ---------- 2.06 Lbs**
    - **Max---------- 2.44 Lbs**
- **After thermal aging**
  - **Mating**
    - **Min ---------- 3.10 Lbs**
    - **Max---------- 3.92 Lbs**
  - **Unmating**
    - **Min ---------- 1.13 Lbs**
    - **Max---------- 1.45 Lbs**

RESULTS Continued

Mating&Unmating durability:

- **Initial**
  - **Mating**
    - **Min ---------- 4.58 Lbs**
    - **Max---------- 5.53 Lbs**
  - **Unmating**
    - **Min ---------- 2.26 Lbs**
    - **Max---------- 2.67 Lbs**
- **After 25 Cycles**
  - **Mating**
    - **Min ---------- 4.69 Lbs**
    - **Max---------- 5.45 Lbs**
  - **Unmating**
    - **Min ---------- 2.30 Lbs**
    - **Max---------- 2.71 Lbs**
- **After 50 Cycles**
  - **Mating**
    - **Min ---------- 4.55 Lbs**
    - **Max---------- 5.34 Lbs**
  - **Unmating**
    - **Min ---------- 2.35 Lbs**
    - **Max---------- 2.77 Lbs**
- **After 75 Cycles**
  - **Mating**
    - **Min ---------- 4.52 Lbs**
    - **Max---------- 5.22 Lbs**
  - **Unmating**
    - **Min ---------- 2.15 Lbs**
    - **Max---------- 2.75 Lbs**
- **After 100 Cycles**
  - **Mating**
    - **Min ---------- 4.51 Lbs**
    - **Max---------- 5.10 Lbs**
  - **Unmating**
    - **Min ---------- 2.20 Lbs**
    - **Max---------- 2.76 Lb**
- **After Humidity**
  - **Mating**
    - **Min ---------- 2.88 Lbs**
    - **Max---------- 3.61 Lbs**
  - **Unmating**
    - **Min ---------- 1.41 Lbs**
    - **Max---------- 2.22 Lbs**

Connector pulls force:

- **0° pull**
  - **Min----------30.47 Lbs**
  - **Max ----------39.41 Lbs**
- **90° pull**
  - **Min----------15.44 Lbs**
  - **Max ----------20.15 Lbs**

RESULTS Continued

LLCR Durability (192 points, include 56 ground and 136 signal pin LLCR test points)

Signal pin:

- **Initial ---------- 62.77 mOhms Max**

Ground pin:

- **Initial ---------- 16.52 mOhms Max**
- **After 100 Cycles**
  - **<= +5.0 mOhms ---------- 188 Points ---------- Stable**
  - **+5.1 to +10.0 mOhms ---------- 4 Points ---------- Minor**
  - **+10.1 to +15.0 mOhms ---------- 0 Points ---------- Acceptable**
  - **+15.1 to +50.0 mOhms ---------- 0 Points ---------- Marginal**
  - **+50.1 to +2000 mOhms ---------- 0 Points ---------- Unstable**
  - **>+2000 mOhms ---------- 0 Points ---------- Open Failure**
- **After thermal shock**
  - **<= +5.0 mOhms ---------- 182 Points ---------- Stable**
  - **+5.1 to +10.0 mOhms ---------- 10 Points ---------- Minor**
  - **+10.1 to +15.0 mOhms ---------- 0 Points ---------- Acceptable**
  - **+15.1 to +50.0 mOhms ---------- 0 Points ---------- Marginal**
  - **+50.1 to +2000 mOhms ---------- 0 Points ---------- Unstable**
  - **>+2000 mOhms ---------- 0 Points ---------- Open Failure**
- **After humidity**
  - **<= +5.0 mOhms ---------- 178 Points ---------- Stable**
  - **+5.1 to +10.0 mOhms ---------- 10 Points ---------- Minor**
  - **+10.1 to +15.0 mOhms ---------- 4 Points ---------- Acceptable**
  - **+15.1 to +50.0 mOhms ---------- 0 Points ---------- Marginal**
  - **+50.1 to +2000 mOhms ---------- 0 Points ---------- Unstable**
  - **>+2000 mOhms ---------- 0 Points ---------- Open Failure**

LLCR Thermal Aging (192 points, include 56 ground and 136 signal pin LLCR test points)

Signal pin:

- **Initial ---------- 60.85 mOhms Max**

Ground pin:

- **Initial ---------- 15.49 mOhms Max**
- **Thermal Aging**
  - **<= +5.0 mOhms ---------- 168 Points ---------- Stable**
  - **+5.1 to +10.0 mOhms ---------- 24 Points ---------- Minor**
  - **+10.1 to +15.0 mOhms ---------- 0 Points ---------- Acceptable**
  - **+15.1 to +50.0 mOhms ---------- 0 Points ---------- Marginal**
  - **+50.1 to +2000 mOhms ---------- 0 Points ---------- Unstable**
  - **>+2000 mOhms ---------- 0 Points ---------- Open Failure**

LLCR Gas Tight (192 points, include 56 ground and 136 signal pin LLCR test points)

Signal pin:

- **Initial ---------- 59.18 mOhms Max**

Ground pin:

- **Initial ---------- 18.72 mOhms Max**
- **Gas-Tight**
  - **<= +5.0 mOhms ---------- 178 Points ---------- Stable**
  - **+5.1 to +10.0 mOhms ---------- 14 Points ---------- Minor**
  - **+10.1 to +15.0 mOhms ---------- 0 Points ---------- Acceptable**
  - **+15.1 to +50.0 mOhms ---------- 0 Points ---------- Marginal**
  - **+50.1 to +2000 mOhms ---------- 0 Points ---------- Unstable**
  - **>+2000 mOhms ---------- 0 Points ---------- Open Failure**

RESULTS Continued

LLCR Mechanical Shock & Vibration (192 points, include 56 ground and 136 signal pin LLCR test points)

Signal pin:

- **Initial ---------- 155.59 mOhms Max**

Ground pin:

- **Initial ---------- 37.08 mOhms Max**
- Shock&Vibration
  - **<= +5.0 mOhms ---------- 190 Points ---------- Stable**
  - **+5.1 to +10.0 mOhms ---------- 1 Points ---------- Minor**
  - **+10.1 to +15.0 mOhms ---------- 0 Points ---------- Acceptable**
  - **+15.1 to +50.0 mOhms ---------- 1 Points ---------- Marginal**
  - **+50.1 to +2000 mOhms ---------- 0 Points ---------- Unstable**
  - **>+2000 mOhms ---------- 0 Points ---------- Open Failure**

Insulation Resistance minimums, IR

Pin-Pin

- **Initial**
  - **Mated ---------- 100000Meg Ω ---------- Pass**
  - **Unmated ---------- 100000Meg Ω ---------- Pass**
- **Thermal**
  - **Mated ---------- 100000Meg Ω ---------- Pass**
  - **Unmated ---------- 100000Meg Ω ---------- Pass**
- **Humidity**
  - **Mated ---------- 50000Meg Ω ---------- Pass**
  - **Unmated ---------- 50000Meg Ω ---------- Pass**

Pin-Ground

- **Initial**
  - **Mated ---------- 100000Meg Ω ---------- Pass**
  - **Unmated ---------- 100000Meg Ω ---------- Pass**
- **Thermal**
  - **Mated ---------- 100000Meg Ω ---------- Pass**
  - **Unmated ---------- 100000Meg Ω ---------- Pass**
- **Humidity**
  - **Mated ---------- 50000Meg Ω ---------- Pass**
  - **Unmated ---------- 50000Meg Ω ---------- Pass**

Row-Row

- **Initial**
  - **Mated ---------- 100000Meg Ω ---------- Pass**
  - **Unmated ---------- 100000Meg Ω ---------- Pass**
- **Thermal**
  - **Mated ---------- 100000Meg Ω ---------- Pass**
  - **Unmated ---------- 100000Meg Ω ---------- Pass**
- **Humidity**
  - **Mated ---------- 100000Meg Ω ---------- Pass**
  - **Unmated ---------- 100000Meg Ω ---------- Pass**

Pin- Closest Metallic Hardware

- **Initial**
  - **Mated ---------- 100000Meg Ω ---------- Pass**
  - **Unmated ---------- 100000Meg Ω ---------- Pass**
- **Thermal**
  - **Mated ---------- 100000Meg Ω ---------- Pass**
  - **Unmated ---------- 100000Meg Ω ---------- Pass**
- **Humidity**
  - **Mated ---------- 100000Meg Ω ---------- Pass**
  - **Unmated ---------- 100000Meg Ω ---------- Pass**

RESULTS Continued

Ground- Closest Metallic Hardware

- **Initial**
  - **Mated---------- 100000Meg Ω ---------- Pass**
  - **Unmated ---------- 100000Meg Ω ---------- Pass**
- **Thermal**
  - **Mated---------- 100000Meg Ω ---------- Pass**
  - **Unmated ---------- 100000Meg Ω ---------- Pass**
- **Humidity**
  - **Mated---------- 100000Meg Ω ---------- Pass**
  - **Unmated ---------- 100000Meg Ω ---------- Pass**

Dielectric Withstanding Voltage minimums, DWV

- **Minimums**
  - **Breakdown Voltage----------600VAC**
  - **Test Voltage ----------450VAC**
  - **Working Voltage ----------150VAC**

Pin - pin

- **Initial DWV ----------Passed**
- **Thermal DWV----------Passed**
- **Humidity DWV----------Passed**

Pin - Ground

- **Initial DWV ----------Passed**
- **Thermal DWV----------Passed**
- **Humidity DWV----------Passed**

Row-Row

- **Initial DWV ----------Passed**
- **Thermal DWV----------Passed**
- **Humidity DWV----------Passed**

Pin- Closest Metallic Hardware

- **Initial DWV ----------Passed**
- **Thermal DWV----------Passed**
- **Humidity DWV----------Passed**

Ground- Closest Metallic Hardware

- **Initial DWV ----------Passed**
- **Thermal DWV----------Passed**
- **Humidity DWV----------Passed**

Mechanical Shock & Random Vibration:

- **Shock**
  - **No Damage---------- ---------- Passed**
  - **50 Nanoseconds---------- ---------- Passed**
- **Vibration**
  - **No Damage---------- ---------- Passed**
  - **50 Nanoseconds---------- ---------- Passed**

RESULTS Continued

Cable Flex test

Insulation Resistance minimums, IR

Pin-Pin

- **Initial**
  - **Mated----------->1000Meg Ω ---------- Pass**
- **After flex cycles**
  - **Mated----------->1000Meg Ω ---------- Pass**

Pin-Ground

- **Initial**
  - **Mated----------->1000Meg Ω ---------- Pass**
- **After flex cycles**
  - **Mated----------->1000Meg Ω ---------- Pass**

Row-Row

- **Initial**
  - **Mated----------->1000Meg Ω ---------- Pass**
- **After flex cycles**
  - **Mated----------->1000Meg Ω ---------- Pass**

Pin - to Closest Metallic Hardware

- **Initial**
  - **Mated----------->1000Meg Ω ---------- Pass**
- **After flex cycles**
  - **Mated----------->1000Meg Ω ---------- Pass**

Dielectric Withstanding Voltage minimums, DWV （450VAC）

Pin - pin

- **Initial DWV ----------Passed**
- **After flex cycles DWV ----------Passed**

Pin - Ground

- **Initial DWV ----------Passed**
- **After flex cycles DWV ----------Passed**

Row-Row

- **Initial DWV ----------Passed**
- **After flex cycles DWV ----------Passed**

Pin to Closest Metallic Hardware

- **Initial DWV ----------Passed**
- **After flex cycles DWV ----------Passed**

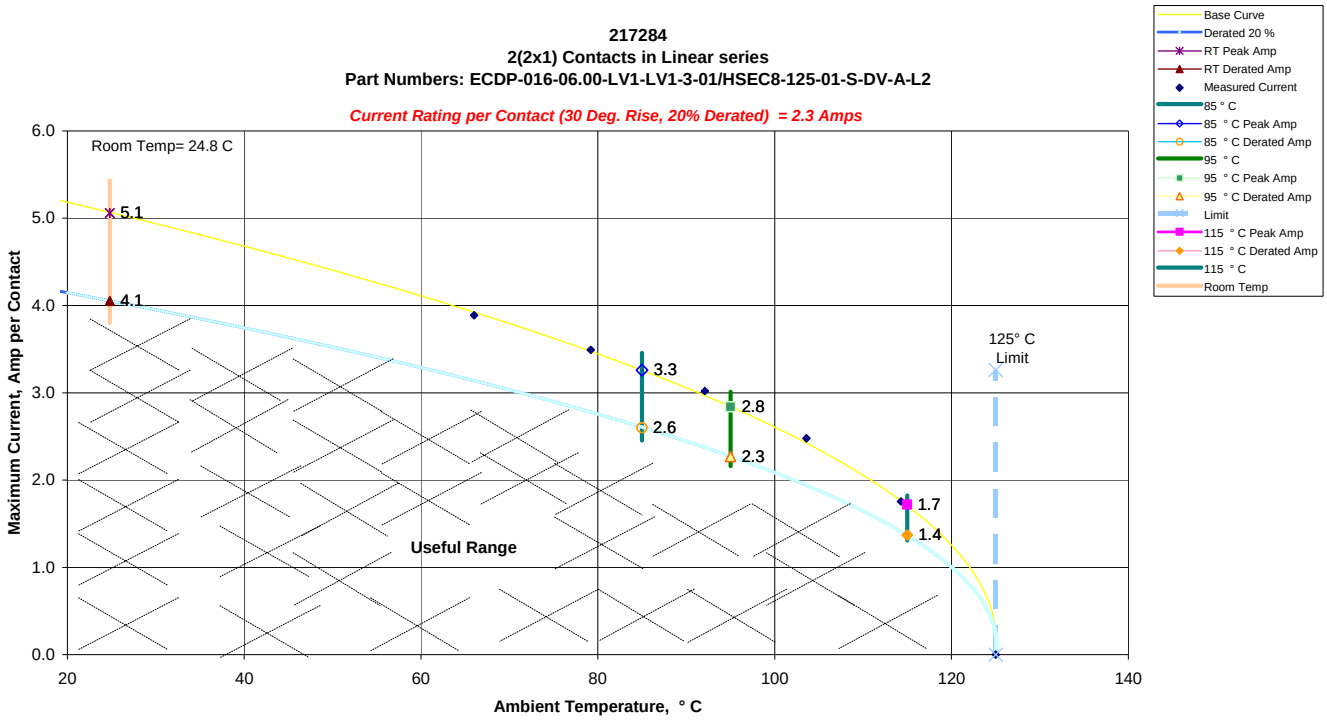
Ground to Closest Metallic Hardware

- **Initial DWV ----------Passed**
- **After flex cycles DWV ----------Passed**

DATA SUMMARIES

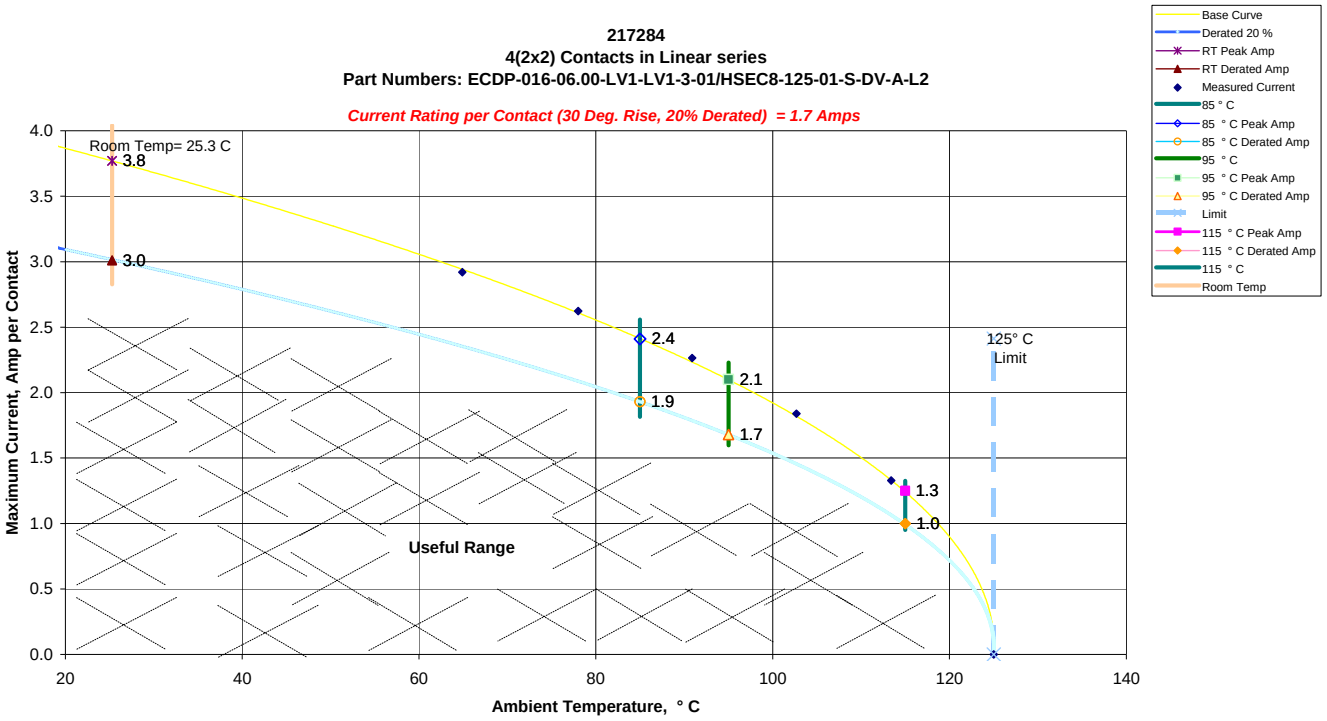
TEMPERATURE RISE (Current Carrying Capacity, CCC):

1) High quality thermocouples whose temperature slopes track one another were used for temperature monitoring.
2) The thermocouples were placed at a location to sense the maximum temperature generated during testing.
3) Temperature readings recorded are those for which three successive readings, 15 minutes apart, differ less than 1° C (computer controlled data acquisition).
4) Adjacent contacts were powered:
    a. Linear configuration with 2 adjacent conductors/contacts powered

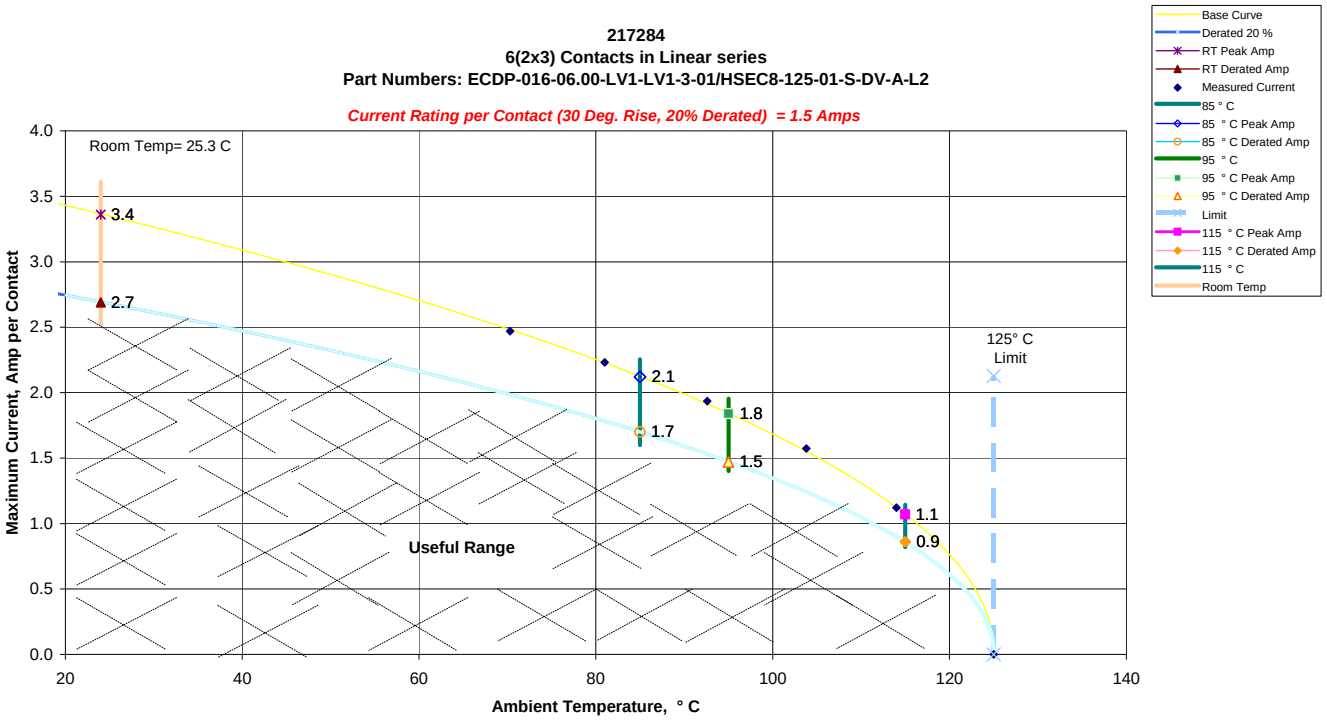


DATA SUMMARIES Continued

b. Linear configuration with 4 adjacent conductors/contacts powered

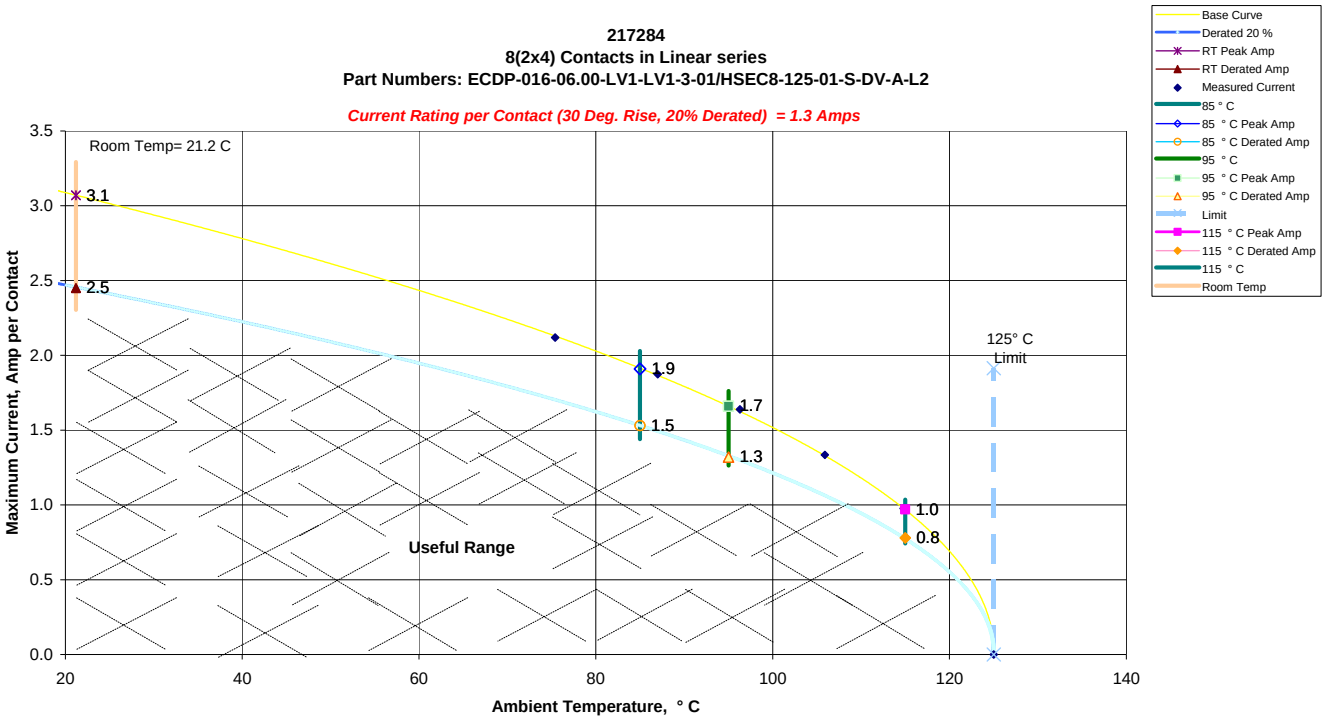


c. Linear configuration with 6 adjacent conductors/contacts powered

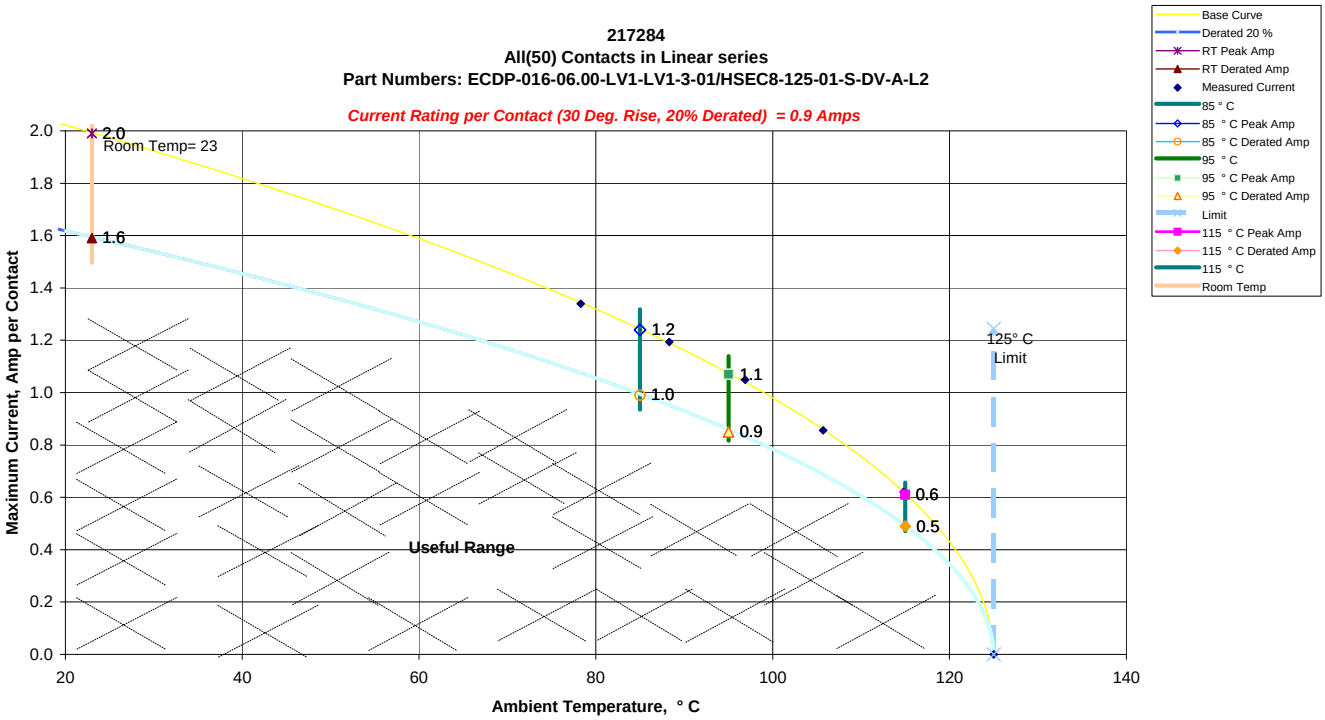


DATA SUMMARIES Continued

d. Linear configuration with 8 adjacent conductors/contacts powered



e. Linear configuration with all adjacent conductors/contacts powered



DATA SUMMARIES Continued

MATING/UNMATING FORCE:

Thermal aging:

	Initial				After Thermals			
	Mating		**Unmating**		**Mating**		**Unmating**	
	Newtons	Force (Lbs)	Newtons	Force (Lbs)	Newtons	Force (Lbs)	Newtons	Force (Lbs)
Minimum	21.62	4.86	9.16	2.06	13.79	3.10	5.03	1.13
Maximum	24.73	5.56	10.85	2.44	17.44	3.92	6.45	1.45
Average	23.30	**5.24**	10.02	**2.25**	15.55	**3.50**	5.55	**1.25**
St Dev	1.08	0.24	0.63	0.14	1.25	0.28	0.51	0.11
Count	8	8	8	8	8	8	8	8

Mating/Unmating durability:

	Initial				After 25 Cycles			
	Mating		**Unmating**		**Mating**		**Unmating**	
	Newtons	Force (Lbs)	Newtons	Force (Lbs)	Newtons	Force (Lbs)	Newtons	Force (Lbs)
Minimum	20.37	4.58	10.05	2.26	20.86	4.69	10.23	2.30
Maximum	24.60	5.53	11.88	2.67	24.24	5.45	12.05	2.71
Average	22.58	**5.08**	11.06	**2.49**	22.40	**5.04**	11.13	**2.50**
St Dev	1.61	0.36	0.66	0.15	1.38	0.31	0.69	0.15
Count	8	8	8	8	8	8	8	8
	After 50 Cycles				After 75 Cycles			
	Mating		**Unmating**		**Mating**		**Unmating**	
	Newtons	Force (Lbs)	Newtons	Force (Lbs)	Newtons	Force (Lbs)	Newtons	Force (Lbs)
Minimum	20.24	4.55	10.45	2.35	20.10	4.52	9.56	2.15
Maximum	23.75	5.34	12.32	2.77	23.22	5.22	12.23	2.75
Average	21.94	**4.93**	11.36	**2.55**	21.46	**4.82**	11.38	**2.56**
St Dev	1.55	0.35	0.67	0.15	1.35	0.30	0.89	0.20
Count	8	8	8	8	8	8	8	8
	After 100 Cycles				After Humidity			
	Mating		**Unmating**		**Mating**		**Unmating**	
	Newtons	Force (Lbs)	Newtons	Force (Lbs)	Newtons	Force (Lbs)	Newtons	Force (Lbs)
Minimum	20.06	4.51	9.79	2.20	12.81	2.88	6.27	1.41
Maximum	22.68	5.10	12.28	2.76	16.06	3.61	9.87	2.22
Average	21.11	**4.75**	11.42	**2.57**	14.01	**3.15**	7.57	**1.70**
St Dev	1.02	0.23	0.83	0.19	0.99	0.22	1.35	0.30
Count	8	8	8	8	8	8	8	8

DATA SUMMARIES Continued

Connector pull force

0° Pull

	Force (lbs)
Minimum	**30.47**
Maximum	39.41
Average	34.51

90° Pull

	Force (lbs)
Minimum	**15.44**
Maximum	20.15
Average	17.69

INSULATION RESISTANCE (IR):

	Pin to Pin		
	Mated	Unmated	Unmated
Minimum	**ECDP/HSEC8**	**ECDP**	**HSEC8**
Initial	100000	100000	100000
Thermal	100000	100000	100000
Humidity	50000	100000	50000

	Pin to Ground		
	Mated	Unmated	Unmated
Minimum	**ECDP/HSEC8**	**ECDP**	**HSEC8**
Initial	100000	100000	100000
Thermal	100000	100000	100000
Humidity	50000	100000	50000

	Ground to Closest Metallic Hardware		
	Mated	Unmated	Unmated
Minimum	**ECDP/HSEC8**	**ECDP**	**HSEC8**
Initial	100000	100000	100000
Thermal	100000	100000	100000
Humidity	100000	100000	100000

DATA SUMMARIES Continued

	Row to Row		
	Mated	Unmated	Unmated
Minimum	**ECDP/HSEC8**	**ECDP**	**HSEC8**
Initial	100000	100000	100000
Thermal	100000	100000	100000
Humidity	100000	100000	100000

	Pin to Closest Metallic Hardware		
	Mated	Unmated	Unmated
Minimum	**ECDP/HSEC8**	**ECDP**	**HSEC8**
Initial	100000	100000	100000
Thermal	100000	100000	100000
Humidity	100000	100000	100000

DIELECTRIC WITHSTANDING VOLTAGE (DWV):

Voltage Rating Summary	
Minimum	**ECDP/HSEC8**
Break Down Voltage	600
Test Voltage	450
Working Voltage	150

Pin to Pin	
Initial Test Voltage	Passed
After Thermal Test Voltage	Passed
After Humidity Test Voltage	Passed

Row to Row	
Initial Test Voltage	Passed
After Thermal Test Voltage	Passed
After Humidity Test Voltage	Passed

Pin to Ground	
Initial Test Voltage	Passed
After Thermal Test Voltage	Passed
After Humidity Test Voltage	Passed

DATA SUMMARIES Continued

Pin to Closest Metallic Hardware	
Initial Test Voltage	Passed
After Thermal Test Voltage	Passed
After Humidity Test Voltage	Passed

Ground to Closest Metallic Hardware	
Initial Test Voltage	Passed
After Thermal Test Voltage	Passed
After Humidity Test Voltage	Passed

Cable flex

INSULATION RESISTANCE (IR):

	Pin to Pin		
	Mated	Unmated	Unmated
Minimum	**ECDP/HSEC8**	**ECDP**	**HSEC8**
Initial	>1000	>1000	>1000
After 500 Flex cycles	>1000	>1000	>1000

	Pin to Ground		
	Mated	Unmated	Unmated
Minimum	**ECDP/HSEC8**	**ECDP**	**HSEC8**
Initial	>1000	>1000	>1000
After 500 Flex cycles	>1000	>1000	>1000

	Ground to Closest Metallic Hardware		
	Mated	Unmated	Unmated
Minimum	**ECDP/HSEC8**	**ECDP**	**HSEC8**
Initial	>1000	>1000	>1000
After 500 Flex cycles	>1000	>1000	>1000

	Row to Row		
	Mated	Unmated	Unmated
Minimum	**ECDP/HSEC8**	**ECDP**	**HSEC8**
Initial	>1000	>1000	>1000
After 500 Flex cycles	>1000	>1000	>1000
	Pin to Closest Metallic Hardware		
	Mated	Unmated	Unmated
Minimum	**ECDP/HSEC8**	**ECDP**	**HSEC8**
Initial	>1000	>1000	>1000
After 500 Flex cycles	>1000	>1000	>1000

DATA SUMMARIES Continued

DIELECTRIC WITHSTANDING VOLTAGE (DWV):

Voltage Rating Summary	
Minimum	**ECDP/HSEC8**
Break Down Voltage	600
Test Voltage	450
Working Voltage	150

Pin to Pin	
Initial Test Voltage	Passed
After Flex Test Voltage	Passed

Row to Row	
Initial Test Voltage	Passed
After Flex Test Voltage	Passed

Pin to Ground	
Initial Test Voltage	Passed
After Flex Test Voltage	Passed

Pin to Closest Metallic Hardware	
Initial Test Voltage	Passed
After Flex Test Voltage	Passed

Ground to Closest Metallic Hardware	
Initial Test Voltage	Passed
After Flex Test Voltage	Passed

DATA SUMMARIES Continued

LLCR Durabiltiy:

1) A total of 192 points were measured.
2) EIA-364-23, *Low Level Contact Resistance Test Procedure for Electrical Connectors and Sockets.*
3) A computer program, *LLCR 221.exe*, ensures repeatability for data acquisition.
4) The following guidelines are used to categorize the changes in LLCR as a result from stressing.
   a. <= +5.0 mOhms: ---------- Stable
   b. +5.1 to +10.0 mOhms:---------- Minor
   c. +10.1 to +15.0 mOhms: ---------- Acceptable
   d. +15.1 to +50.0 mOhms: ---------- Marginal
   e. +50.1 to +2000 mOhms ---------- Unstable
   f. >+2000 mOhms:---------- Open Failure

	LLCR Measurement Summaries by Pin Type			
Date	9/2/2012	9/5/2012	9/12/2012	9/25/2012
Room Temp (Deg C)	23	23	23	23
Rel Humidity (%)	56	56	56	60
Technician	Peter Chen	Peter Chen	Peter Chen	Peter Chen
mOhm values	**Actual Initial**	**Delta 100 Cycles**	**Delta Therm Shck**	**Delta Humidity**
	Pin Type 1: Signal			
Average	50.56	1.34	1.63	1.60
St. Dev.	4.24	1.62	1.48	2.07
Min	42.71	0.01	0.02	0.00
Max	62.77	6.59	6.71	11.36
Summary Count	136	136	136	136
Total Count	136	136	136	136
	Pin Type 2: Ground			
Average	13.32	0.88	1.33	1.46
St. Dev.	1.02	0.78	0.85	1.02
Min	11.72	0.01	0.03	0.04
Max	16.52	3.64	2.90	3.59
Summary Count	56	56	56	56
Total Count	56	56	56	56

LLCR Delta Count by Category						
	Stable	**Minor**	**Acceptable**	**Marginal**	**Unstable**	**Open**
mOhms	**<=5**	**>5 & <=10**	**>10 & <=15**	**>15 & <=50**	**>50 & <=1000**	**>1000**
100 Cycles	**188**	**4**	**0**	**0**	**0**	**0**
Therm Shck	**182**	**10**	**0**	**0**	**0**	**0**
Humidity	**178**	**10**	**4**	**0**	**0**	**0**

DATA SUMMARIES Continued

LLCR thermal aging

1) A total of 192 points were measured
2) EIA-364-23, *Low Level Contact Resistance Test Procedure for Electrical Connectors and Sockets.*
3) A computer program, *LLCR 221.exe*, ensures repeatability for data acquisition.
4) The following guidelines are used to categorize the changes in LLCR as a result from stressing.
   a. <= +5.0 mOhms: ---------- Stable
   b. +5.1 to +10.0 mOhms:---------- Minor
   c. +10.1 to +15.0 mOhms: ---------- Acceptable
   d. +15.1 to +50.0 mOhms: ---------- Marginal
   e. +50.1 to +2000 mOhms ---------- Unstable
   f. >+2000 mOhms:---------- Open Failure

LLCR Measurement Summaries by Pin Type				
Date	9/2/2012	9/14/2012		
Room Temp (Deg C)	23	23		
Rel Humidity (%)	56	56		
Technician	Peter Chen	Peter Chen		
mOhm values	**Actual Initial**	**Delta Thermal**	**Delta**	**Delta**
	Pin Type 1: Signal			
Average	50.40	2.77		
St. Dev.	4.00	1.82		
Min	42.71	0.02		
Max	60.85	7.88		
Summary Count	136	136		
Total Count	136	136		
	Pin Type 2:			
Average	13.32	1.98		
St. Dev.	0.90	1.28		
Min	11.70	0.09		
Max	15.49	5.68		
Summary Count	56	56		
Total Count	56	56		

LLCR Delta Count by Category						
	Stable	**Minor**	**Acceptable**	**Marginal**	**Unstable**	**Open**
mOhms	**<=5**	**>5 & <=10**	**>10 & <=15**	**>15 & <=50**	**>50 & <=1000**	**>1000**
Thermal	**168**	**24**	**0**	**0**	**0**	**0**

DATA SUMMARIES Continued

LLCR GAS TIGHT:

1) A total of 192 points were measured
2) EIA-364-23, *Low Level Contact Resistance Test Procedure for Electrical Connectors and Sockets.*
3) A computer program, *LLCR 221.exe*, ensures repeatability for data acquisition.
4) The following guidelines are used to categorize the changes in LLCR as a result from stressing.
   a. <= +5.0 mOhms: ---------- Stable
   b. +5.1 to +10.0 mOhms:---------- Minor
   c. +10.1 to +15.0 mOhms: ---------- Acceptable
   d. +15.1 to +50.0 mOhms: ---------- Marginal
   e. +50.1 to +2000 mOhms: ---------- Unstable
   f. >+2000 mOhms:---------- Open Failure

LLCR Measurement Summaries by Pin Type				
Date	9/24/2012	9/26/2012		
Room Temp (Deg C)	23	23		
Rel Humidity (%)	58	61		
Technician	Peter Chen	Peter Chen		
mOhm values	**Actual Initial**	**Delta Acid Vapor**	**Delta**	**Delta**
	Pin Type 1: Signal			
Average	50.63	2.60		
St. Dev.	3.82	1.72		
Min	43.68	0.01		
Max	59.18	7.87		
Summary Count	136	136		
Total Count	136	136		
	Pin Type 2: Ground			
Average	13.42	1.75		
St. Dev.	1.23	1.60		
Min	11.99	0.01		
Max	18.72	6.69		
Summary Count	56	56		
Total Count	56	56		

LLCR Delta Count by Category						
	Stable	**Minor**	**Acceptable**	**Marginal**	**Unstable**	**Open**
mOhms	**<=5**	**>5 & <=10**	**>10 & <=15**	**>15 & <=50**	**>50 & <=1000**	**>1000**
Acid Vapor	**178**	**14**	**0**	**0**	**0**	**0**

DATA SUMMARIES Continued

LLCR Mechanical Shock & Vibration:

1) A total of 192 points were measured
2) EIA-364-23, *Low Level Contact Resistance Test Procedure for Electrical Connectors and Sockets.*
3) A computer program, *LLCR 221.exe*, ensures repeatability for data acquisition.
4) The following guidelines are used to categorize the changes in LLCR as a result from stressing.
   a. <= +5.0 mOhms: ---------- Stable
   b. +5.1 to +10.0 mOhms:---------- Minor
   c. +10.1 to +15.0 mOhms: ---------- Acceptable
   d. +15.1 to +50.0 mOhms: ---------- Marginal
   e. +50.1 to +2000 mOhms: ---------- Unstable
   f. >+2000 mOhms:---------- Open Failure

LLCR Measurement Summaries by Pin Type				
Date	10/3/2012	10/8/2012		
Room Temp (Deg C)	22	22		
Rel Humidity (%)	37	31		
Technician	Troy Cook	Troy Cook		
mOhm values	**Actual Initial**	**Delta Shock-Vib**	**Delta**	**Delta**
	Pin Type 1: Signal			
Average	140.29	0.79		
St. Dev.	4.75	1.68		
Min	134.00	0.01		
Max	155.59	19.02		
Summary Count	136	136		
Total Count	136	136		
	Pin Type 2: Ground			
Average	31.50	0.90		
St. Dev.	1.22	1.18		
Min	29.30	0.02		
Max	37.08	6.55		
Summary Count	56	56		
Total Count	56	56		

LLCR Delta Count by Category						
	Stable	**Minor**	**Acceptable**	**Marginal**	**Unstable**	**Open**
mOhms	**<=5**	**>5 & <=10**	**>10 & <=15**	**>15 & <=50**	**>50 & <=1000**	**>1000**
Shock-Vib	**190**	**1**	**0**	**1**	**0**	**0**

Shock Vibration Event Detection

Shock and Vibration Event Detection Summary	
Contacts tested	30
Test Condition	C, 100g's, 6ms, Half-Sine
Shock Events	0
Test Condition	V-B, 7.56 rms g
Vibration Events	0
Total Events	0

EQUIPMENT AND CALIBRATION SCHEDULES

Equipment #: HZ-MO-05
Description: Digital Multimeter
Manufacturer: Keithley
Model: 3706
Serial #: 1285188
Accuracy: Last Cal: 2012-8-18, Next Cal: 2013-8-18

Equipment #: HZ-TCT-01
Description: Normal force analyzer
Manufacturer: Mecmesin Multitester
Model: Mecmesin Multitester 2.5-i
Serial #: 08-1049-04
Accuracy: Last Cal: 2012-4-28, Next Cal: 2013-4-27

Equipment #: HZ-OV-01
Description: Oven
Manufacturer: Huida
Model: CS101-1E
Serial #: CS101-1E-B
Accuracy: Last Cal: 2011-12-14, Next Cal: 2012-12-13

Equipment #: HZ-THC-01
Description: Humidity transmitter
Manufacturer: Thermtron
Model: HMM30C
Serial #: D0240037
Accuracy: Last Cal: 2012-3-3, Next Cal: 2013-3-2

Equipment #: HZ-HPM-01
Description: IR/DWV Tester
Manufacturer: AN9636H
Model: AN9636H
Serial #: 089601091
Accuracy: Last Cal: 2012-7-6, Next Cal: 2013-7-5

Equipment #: HZ-MO-01
Description: Micro-ohmmeter
Manufacturer: Keithley
Model: 2700
Serial #: 1199807
Accuracy: Last Cal: 2012-4-28, Next Cal: 2013-4-27

EQUIPMENT AND CALIBRATION SCHEDULES Continued

Equipment #: HZ-PS-01
Description: Power Supply
Manufacturer: Agilent
Model: 6031A
Serial #: MY41000982
Accuracy: Last Cal: 2012-4-28, Next Cal: 2013-4-27

Equipment #: HZ-TSC-01
Description: Thermal Shock transmitter
Manufacturer: CSZ
Model: 10-VT14994
Serial #: VTS-3-6-6-SC/AC
Accuracy: Last Cal: 2012-11-1, Next Cal: 2013-11-1

Equipment #: SVC-01
Description: Shock & Vibration Table
Manufacturer: Data Physics
Model: LE-DSA-10-20K
Serial #: 10037
Accuracy: See Manual
… Last Cal: 2011-11-31, Next Cal: 2012-11-31

Equipment #: ACLM-01
Description: Accelerometer
Manufacturer: PCB Piezotronics
Model: 352C03
Serial #: 115819
Accuracy: See Manual
… Last Cal: 2012-7-9, Next Cal: 2013-7-9

Equipment #: ED-03
Description: Event Detector
Manufacturer: Analysis Tech
Model: 32EHD
Serial #: 1100604
Accuracy: See Manual
… Last Cal: 2012-6-4, Next Cal: 2013-6-4

Equipment #: HDR - 01
Description: HDR Flex Tester
Manufacturer: Samtec Inc
Model: AT-1440-000
Accuracy: No Calibration Required